

# Silicone (Z9)

Heat Sink Compound is silicone-based thermal grease made from a silicone fluid thickened with metal oxide fillers.

## FEATURES:

Grease-like consistency; opaque white in color; zero bleed; very stable at elevated temperatures; excellent thermal resistance and high thermal conductivity; efficient thermal coupler; effective and positive heat sink sealers and heat transfer agent. The product offers high thermal conductivity, virtually no bleed or evaporation over a wide operating temperature range. It will not harden, dry out or melt after 1,000 hours at 200°C.

Mil. Spec. C-47113

## Typical Properties:

Property	Value	Test Method
Consistency (Penetration, worked, 60x)	340	ASTM D-217
Specific Gravity, @ 25°C	2.2	ASTM D-70
Bleed, @ 200°C, 24 Hrs., %/Wt	0.50	FTM-321 MODIFIED
Evaporation, @ 200°C, 24 Hrs., %/Wt.	0.50	FTM-321 MODIFIED
Thermal Conductivity, @ 36°C W/m-K	0.70	ASTM D-5470-06
<b>Electrical Properties</b>		
Dielectric strength, 0.05" gap, V/mil	400	ASTM D-149
Dielectric constant, 25°C @ 1,000 Hz	4.90	ASTM D-150
Dissipation factor, 25°C @ 1,000 Hz	0.0011	ASTM D-150
Volume Resistivity, ohm-cm	1.96 x 10 <sup>15</sup>	ASTM D-257
Operating Temperature Range	-55°C to 205°C	
Flow Rate grams/min. @ 50PSI	5-18	
Appearance	White Paste	

## Product Availability:

PART NO.	DESCRIPTION	SIZE	Upc:
10-8109	Heat Sink Silicone	1 oz.	010151132987
10-8108	Heat Sink Silicone	6.5 gm Tube	010151131638
10-8106	Heat Sink Silicone	1 lb. Jar	010151134110



PART No: **10-8109**



PART No: **10-8108**



PART No: **10-8106**

## APPLICATIONS:

Mounting transistors, diodes, rectifiers and resistors. Thermal joint compound for any device where efficient cooling is desired.



HTS: 3212.90.0050

CoO: USA

ECCN: EAR99